



Material Content Data Sheet



Sales Product Name		ICE1CS02G		Issued		29. August 2013		
MA#		MA001051868						
Package		PG-DSO-16-22		Weight*		169.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.475	2.05	2.05	20457	20457
leadframe	inorganic material	phosphorus	7723-14-0	0.021	0.01		121	
	non noble metal	zinc	7440-66-6	0.082	0.05		484	
	non noble metal	iron	7439-89-6	1.644	0.97		9675	
wire	non noble metal	copper	7440-50-8	66.740	39.29	40.32	392862	403142
	noble metal	gold	7440-57-5	0.288	0.17	0.17	1694	1694
encapsulation	organic material	carbon black	1333-86-4	0.282	0.17		1661	
	plastics	epoxy resin	-	9.121	5.37		53693	
	inorganic material	silicondioxide	60676-86-0	84.632	49.80	55.34	498183	553537
leadfinish	non noble metal	tin	7440-31-5	1.562	0.92	0.92	9196	9196
plating	noble metal	silver	7440-22-4	0.404	0.24	0.24	2377	2377
glue	plastics	acrylic resin	-	0.326	0.19		1919	
	noble metal	silver	7440-22-4	1.304	0.77	0.96	7678	9597
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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